

MATERIAL DECLARATION SHEET



Material Number	CAT10A-X2LF Series			
Product Line	Thick Film Chip Resistors Arrays			
Compliance Date	2019/04/11			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [gram]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.000818897	Aluminum oxide	1344-28-1	96%	76%	79.300%
				Magnesium oxide	1309-48-4	3%	2.38%	
				Silicon dioxide	14808-60-7	1%	0.87%	
2	Conductor Layer	Conductor Layer	0.000039074	Silver	7440-22-4	86%	3.24%	3.77%
				Palladium	7440-05-3	1%	0.03%	
				Glass	65997-17-3	13%	0.50%	
3	Resistive Element	Resistive Element	0.000025946	Ruthenium(IV) oxide	12036-10-1	33%	0.84%	2.52%
				Silver	7440-22-4	17%	0.42%	
				Palladium	7440/5/3	25%	0.63%	
				Lead-containing glass	7439-92-1	25%	0.63%	
4	Over Coating	Epoxy	0.000024705	Epoxy resin	25068-38-6	53%	1.02	1.93%
				Talc	14807-96-6	12%	0.23	
				Silicon dioxide	60676-86-0	35%	0.68	
5	End Terminal	Ni-Cr	0.000037007	Nickel	7440-02-0	80%	2.86%	3.58%
				Chromium	7440-47-3	20%	0.72%	
7	Ni Plating	Nickel	0.000048377	Nickel	7440-02-0	100%	4.68%	4.68%
8	Sn Plating	Tin	0.000039694	Tin	7440-31-5	100%	3.84%	3.84%

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TOTAL WEIGHT	0.0010337
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This Document was updated on: 2019/04/11

Important remarks: It is the responsibility of the user to verify they are accessing the latest version.